ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES international and Pan-American co	ourn, Illinois. All righ	hts reserved under both	h This docume level parts, t	ent is a declaratio the declaration en	n of the substance compasses all low	es within the manufacture ver level materials for wh	er listed item. Not hich the manufact	te: if the item is an as urer has engineering	sembly with lower responsibility.		
IPC Web Site for Information on I http://www.ipc.org/IPC-175x	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute			* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
Supplier Information											
mpany name* Company unique ID				Unique ID Authority			Response Date*				
semi								2023-06-08			
Contact Name	Title - Contact		Phone - Contact*			Email - Contact*					
Product-Env-Stewards	oduct-Env-Stewards Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative				Phone - Representative*			Email - Representative*				
Product-Env-Stewards	ompliance	NA				Product-Env-Stewards@onsemi.com					
Requester Item Number Mfr Item	Number Mfr	Mfr Item Name		Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type		
NCV427	CV4276DT33RKG ANA LDO REG			2023-06-08		MY1	350.99	mg	Each		
Manufacturing Proccess Information						·					
Terminal Plating / Grid Array Material	al Terminal Base Alloy J-STD-02		20 MSL Rating	Peak Process Body Temperature Max Time at Pea			k Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU Alloy 1				260	С	30	seconds 3				
Comments											
evel 1 - maximum time at peak temperature during so	Idering is 10-30 seco	onds									
For more information regarding material composition	please refer to page	e 3									

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl hthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).								
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier is a averted or the absence of such written agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.2	mg	Supplier	Silicon (Si)	7440-21-3		0.2	mg
Die Attach	1.4	mg	А	Lead (Pb)	7439-92-1	7a	1.33	mg
			Supplier	Tin (Sn)	7440-31-5		0.07	mg
Lead Frame	214.64	mg	В	Nickel (Ni)	7440-02-0		0.4293	mg
			Supplier	Copper (Cu)	7440-50-8		214.2107	mg
Mold Compound-Black	129.65	mg		Phenolic Resin	proprietary data		10.372	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		10.372	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6482	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		108.2577	mg
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Cu	1.37	mg	Supplier	Copper (Cu)	7440-50-8		1.37	mg